



FQB13N06L / FQI13N06L

60V LOGIC N-Channel MOSFET

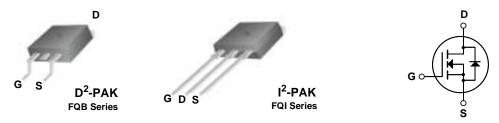
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- 13.6A, 60V, $R_{DS(on)} = 0.11\Omega @V_{GS} = 10 \text{ V}$
- Low gate charge (typical 4.8 nC)
- Low Crss (typical 17 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- 175°C maximum junction temperature rating



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB13N06L / FQI13N06L	Units
V _{DSS}	Drain-Source Voltage		60	V
I _D	Drain Current - Continuous (T _C = 25°	°C)	13.6	Α
	- Continuous (T _C = 100	O°C)	9.6	А
I _{DM}	Drain Current - Pulsed	(Note 1)	54.4	Α
V _{GSS}	Gate-Source Voltage		± 20	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	90	mJ
I _{AR}	Avalanche Current	(Note 1)	13.6	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
P_{D}	Power Dissipation (T _A = 25°C) *		3.75	W
	Power Dissipation (T _C = 25°C)		45	W
	- Derate above 25°C		0.3	W/°C
T _J , T _{STG}	Operating and Storage Temperature Ra	nge	-55 to +175	°C
TL	Maximum lead temperature for soldering 1/8" from case for 5 seconds	g purposes,	300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.35	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°	C	0.05		V/°C
I _{DSS}	Zoro Coto Voltogo Proin Current	V _{DS} = 60 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 48 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.5	V
R _{DS(on)}	Static Drain-Source	V _{GS} = 10 V, I _D = 6.8 A		0.088	0.11	-
D3(0H)	On-Resistance	V _{GS} =5 V, I _D =6.8 A		0.110	0.14	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 25 \text{ V}, I_{D} = 6.8 \text{ A}$ (Note	4)	7		S
Dynam	ic Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		270	350	pF
Coss	Output Capacitance	f = 1.0 MHz		95	125	pF
C _{rss}	Reverse Transfer Capacitance			17	23	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V 00 V I 00 A		8	25	ns
t _r	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 6.8 \text{ A},$		90	190	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$		20	50	ns
t _f	Turn-Off Fall Time	(Note 4,	5)	40	90	ns
Q _g	Total Gate Charge	V _{DS} = 48 V, I _D = 13.6 A,		4.8	6.4	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = 5 \text{ V}$		1.6		nC
Q _{gd}	Gate-Drain Charge	(Note 4,	5)	2.7		nC
	-			ı		
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Dic	ode Forward Current			13.6	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F				54.4	Α
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 13.6 \text{ A}$			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 13.6 \text{ A},$		45		ns
		1				

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 570μH, I_{AS} = 13.6A, V_{DD} = 25V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} \leq 13.6A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

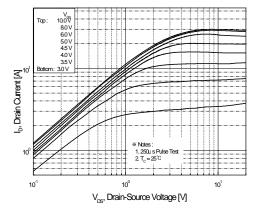


Figure 1. On-Region Characteristics

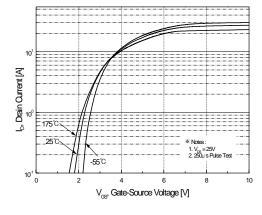


Figure 2. Transfer Characteristics

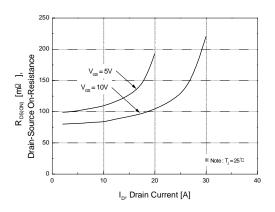


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

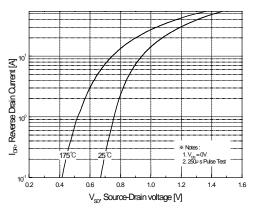


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

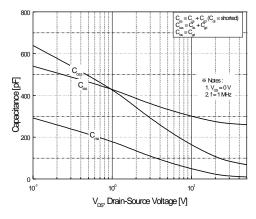


Figure 5. Capacitance Characteristics

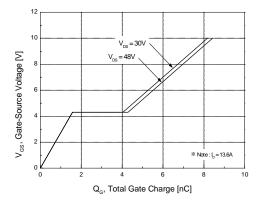


Figure 6. Gate Charge Characteristics

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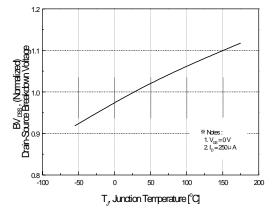


Figure 7. Breakdown Voltage Variation vs. Temperature

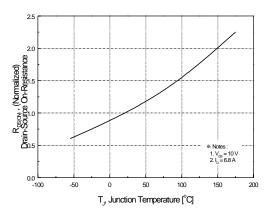


Figure 8. On-Resistance Variation vs. Temperature

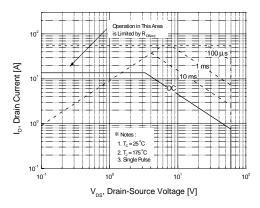


Figure 9. Maximum Safe Operating Area

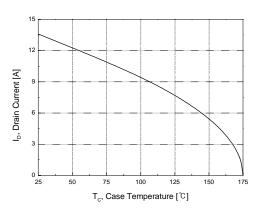


Figure 10. Maximum Drain Current vs. Case Temperature

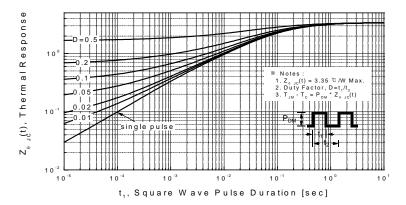
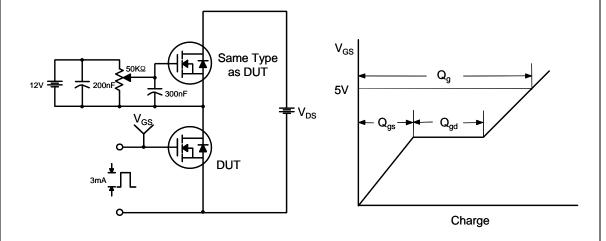


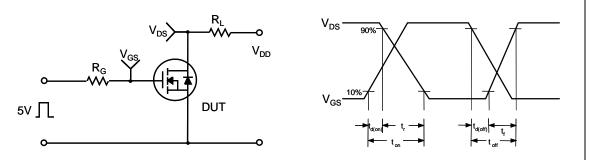
Figure 11. Transient Thermal Response Curve

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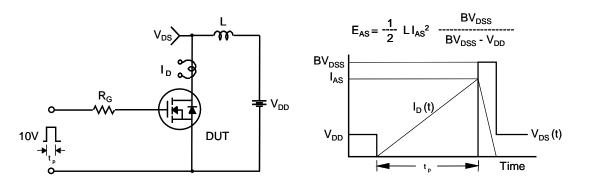
Gate Charge Test Circuit & Waveform



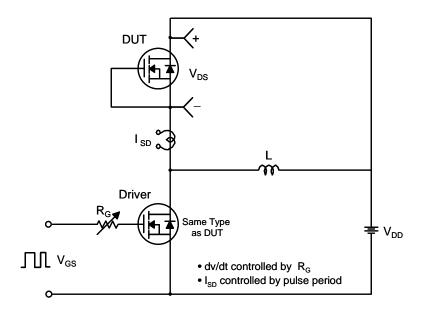
Resistive Switching Test Circuit & Waveforms

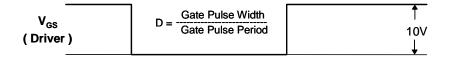


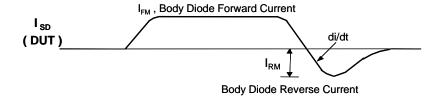
Unclamped Inductive Switching Test Circuit & Waveforms



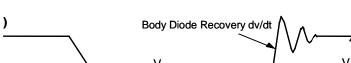
Peak Diode Recovery dv/dt Test Circuit & Waveforms





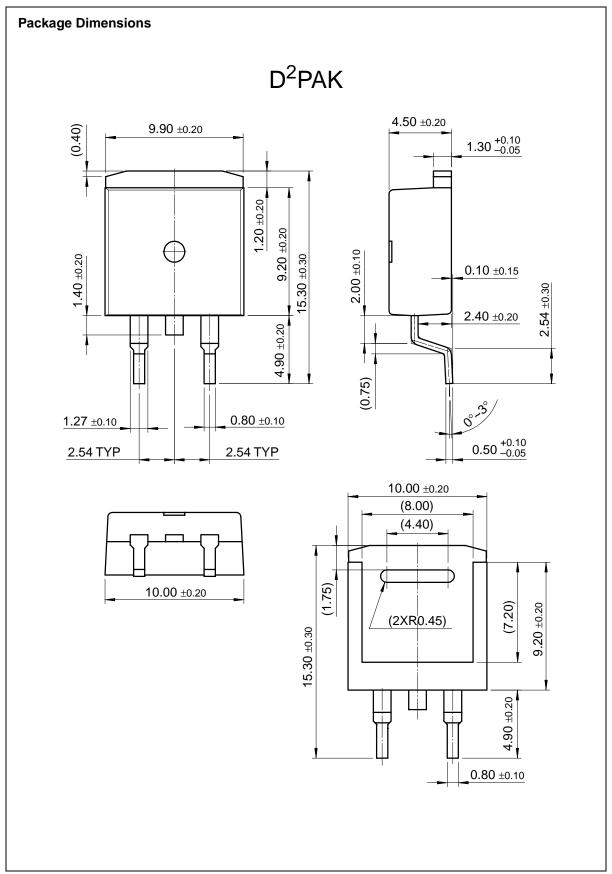


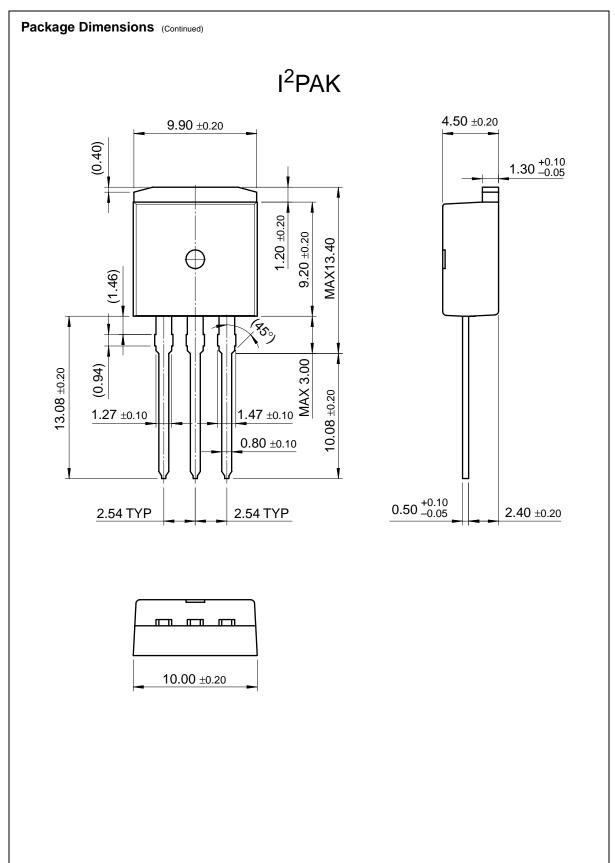
 \mathbf{V}_{DS}



(DUT) **Body Diode** Forward Voltage Drop

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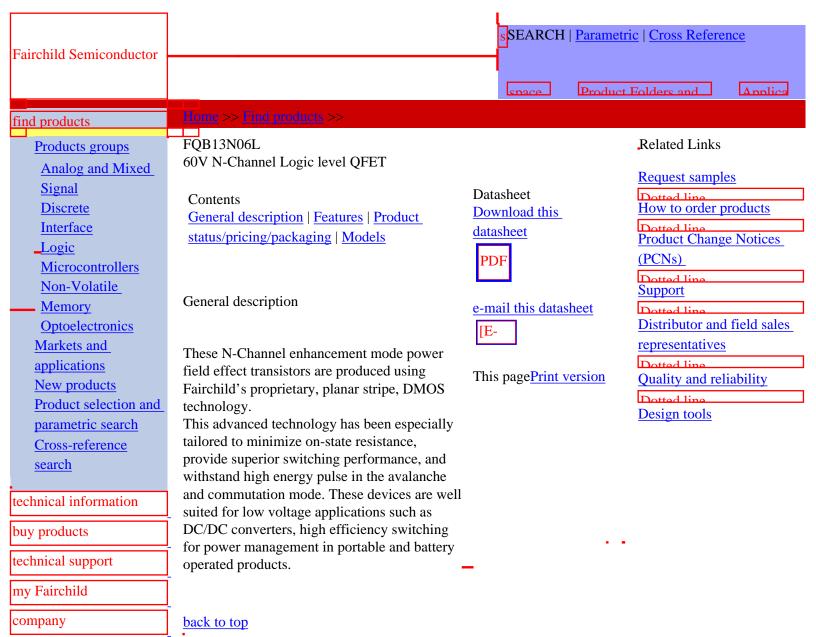
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Datasheet Identification	Product Status	Definition
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Features

- 13.6A, 60V, $R_{DS(on)} = 0.11\Omega$ @ $V_{GS} = 10 \text{ V}$
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- 175°C maximum junction temperature rating

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQB13N06LTM	Full Production	\$0.471	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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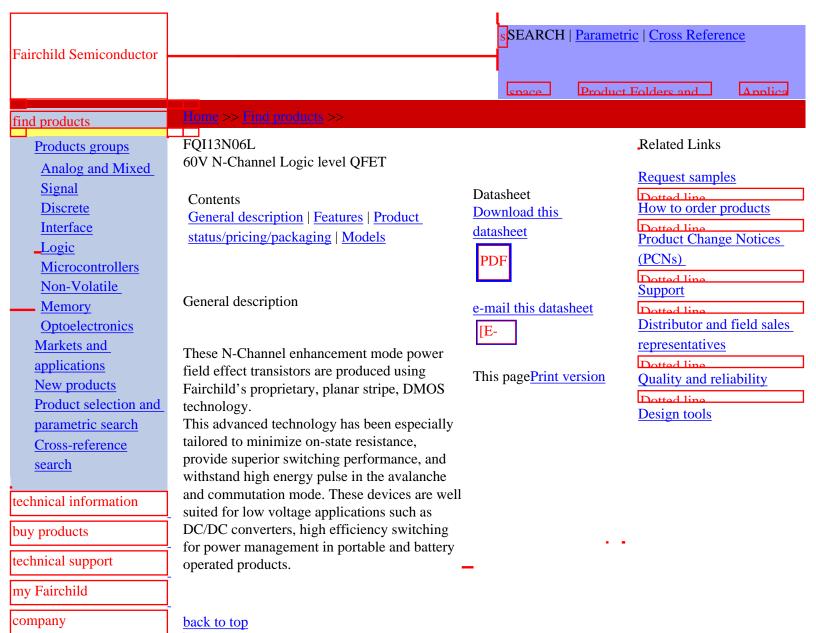
Models

Package & leads	Condition	Temperature range	Software version	Revision date		
PSPICE						
TO-263(D2PAK)-2	Electrical	25°C	9.2	Apr 29, 2002		

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQI13N06LTU	Full Production	\$0.471	TO-262(I2PAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

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Models

Package & leads Condition		Temperature range	Software version	Revision date	
PSPICE					
TO-262(I2PAK)-3	Electrical	25°C	9.2	Apr 29, 2002	

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